



ATTORNEY DOCKET NO.: AGX-14-CPA

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of Gat et al.)

Serial No.: 09/226,396)

Filed: January 6, 1999)

For: HEATING DEVICE FOR)
HEATING SEMICONDUCTOR)
WAFERS IN THERMAL)
PROCESSING CHAMBERS)

Examiner: NGUYEN, KIET

Art Unit: 2881

Commissioner for Patents
Box AF
Washington, D.C. 20231

AMENDMENT AFTER FINAL

Dear Sir:

In response to the Office Action dated June 11, 2002, please amend the above-captioned application as follows:

IN THE CLAIMS

Please cancel claims 34 and 57.

Please amend claims 32, 37 and 51 to read as follows (marked changes included as

Appendix A):

32. An apparatus for heat treating semiconductor wafers comprising:
- a thermal processing chamber adapted to contain a semiconductor wafer; and
- a heating device in communication with said thermal processing chamber for heating a semiconductor wafer in said chamber, said heating device comprising:

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